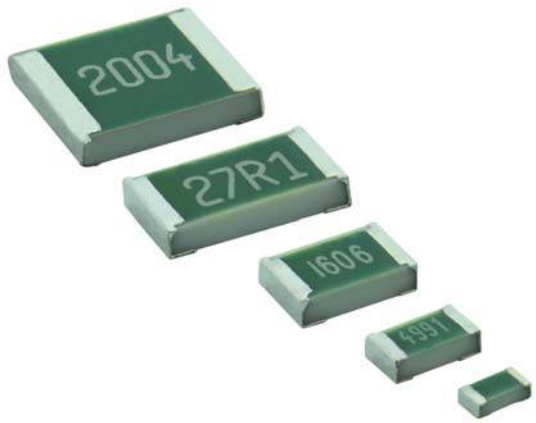
High Stability Thin Film Flat Chip Resistors



TNPW e3 precision thin film flat chip resistors are the perfect choice for most fields of modern electronics where highest reliability and stability is of major concern. Typical applications include test and measuring equipment, medical equipment, industrial, and automotive.

FEATURES

- Superior moisture resistivity (85 °C; 85 % RH)
- Excellent overall stability at different environmental conditions ≤ 0.05 % (1000 h rated power at 70 °C)
- AEC-Q200 qualified (sizes 0402 to 1206)
- Single lot date code (optional)
- Sulfur resistance verified according to ASTM B 809
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

AUTOMOTIVE GRADE

RoHS COMPLIANT

HALOGEN FREE

APPLICATIONS

- Test and measuring equipment
- Medical equipment
- Industrial equipment
- Automotive

TECHNICAL SPECIFICATIONS

DESCRIPTION	TNPW0402 e3	TNPW0603 e3	TNPW0805 e3	TNPW1206 e3	TNPW1210 e3 (1)
DIN size	0402	0603	0805	1206	1210
Metric size code	RR 1005M	RR 1608M	RR 2012M	RR 3216M	RR 3225M
Resistance range	10 Ω to 100 kΩ	10 Ω to 332 kΩ	10 Ω to 1 MΩ	10 Ω to 2 MΩ	10 Ω to 3.01 MΩ
Resistance tolerance	± 1 %; ± 0.5 %; ± 0.1 %				
Temperature coefficient	± 50 ppm/K; ± 25 ppm/K; ± 15 ppm/K; ± 10 ppm/K				
Rated dissipation, P_{70} (2)	0.063 W	0.1 W	0.125 W	0.25 W	0.33 W
Operating voltage, $U_{max.}$ AC_{RMS} or DC	50 V	75 V	150 V	200 V	200 V
Permissible film temperature, $\vartheta_{F\,max.}$ (2)	155 °C				
Operating temperature range	-55 °C to 125 °C (155 °C)				
Insulation voltage:					
1 min; U_{ins}	75 V	100 V	200 V	300 V	300 V
Continuous	75 V	75 V	75 V	75 V	75 V
Failure rate: $FIT_{observed}$	≤ 0.1 x 10^{-9}/h				

Notes

(1) Size not specified in EN 140401-801.

(2) Please refer to APPLICATION INFORMATION below.

APPLICATION INFORMATION

The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-circuit board (thermal resistance). The rated dissipation applies only if the permitted film temperature is not exceeded. Furthermore, a high level of ambient temperature or of power dissipation may raise the temperature of the solder joint, hence special solder alloys or board materials may be required to maintain the reliability of the assembly.

These resistors do not feature a limited lifetime when operated within the permissible limits. However, resistance value drift increasing over operating time may result in exceeding a limit acceptable to the specific application, thereby establishing a functional lifetime. The designer may estimate the performance of the particular resistor application or set certain load and temperature limits in order to maintain a desired stability.

MAXIMUM RESISTANCE CHANGE AT RATED DISSIPATION		
OPERATION MODE		**STANDARD**
Rated dissipation	**TNPW0402 e3**	0.063 W
	TNPW0603 e3	0.1 W
	TNPW0805 e3	0.125 W
	TNPW1206 e3	0.25 W
	TNPW1210 e3	0.33 W
Film temperature, $\vartheta_{F\ max.}$		125 °C
Max. resistance change at rated dissipation for resistance range:	**TNPW0402 e3**	10 Ω to 100 kΩ
	TNPW0603 e3	10 Ω to 332 kΩ
	TNPW0805 e3	10 Ω to 1 MΩ
	TNPW1206 e3	10 Ω to 2 MΩ
	TNPW1210 e3	10 Ω to 3.01 MΩ
$\lvert\Delta R/R\rvert_{max.}$, after:		
	1000 h	≤ 0.05 %
	8000 h	≤ 0.10 %
	225 000 h	≤ 0.30 %

TEMPERATURE COEFFICIENT AND RESISTANCE RANGE				
TYPE	**TCR**	**TOLERANCE**	**RESISTANCE**	**E-SERIES**
TNPW0402 e3	± 50 ppm/K	± 1 %	10 Ω to 100 kΩ	E24; E96
		± 0.5 %	10 Ω to 100 kΩ	E24; E192
		± 0.1 %	47 Ω to 100 kΩ	
	± 25 ppm/K	± 1 %	10 Ω to 100 kΩ	E24; E96
		± 0.5 %	10 Ω to 100 kΩ	E24; E192
		± 0.1 %	47 Ω to 100 kΩ	
	± 15 ppm/K	± 0.1 %		
	± 10 ppm/K	± 0.1 %		
TNPW0603 e3	± 50 ppm/K	± 1 %	10 Ω to 332 kΩ	E24; E96
		± 0.5 %	10 Ω to 332 kΩ	E24; E192
		± 0.1 %		
	± 25 ppm/K	± 1 %	10 Ω to 332 kΩ	E24; E96
		± 0.5 %	10 Ω to 332 kΩ	E24; E192
		± 0.1 %		
	± 15 ppm/K	± 0.1 %	47 Ω to 332 kΩ	
	± 10 ppm/K	± 0.1 %		
TNPW0805 e3	± 50 ppm/K	± 1 %	10 Ω to 1 MΩ	E24; E96
		± 0.5 %	10 Ω to 1 MΩ	E24; E192
		± 0.1 %		
	± 25 ppm/K	± 1 %	10 Ω to 1 MΩ	E24; E96
		± 0.5 %	10 Ω to 1 MΩ	E24; E192
		± 0.1 %		
	± 15 ppm/K	± 0.1 %	47 Ω to 1 MΩ	
	± 10 ppm/K	± 0.1 %		
TNPW1206 e3	± 50 ppm/K	± 1 %	10 Ω to 2 MΩ	E24; E96
		± 0.5 %	10 Ω to 2 MΩ	E24; E192
		± 0.1 %		
	± 25 ppm/K	± 1 %	10 Ω to 2 MΩ	E24; E96
		± 0.5 %	10 Ω to 2 MΩ	E24; E192
		± 0.1 %		
	± 15 ppm/K	± 0.1 %	47 Ω to 2 MΩ	
	± 10 ppm/K	± 0.1 %		
TNPW1210 e3	± 50 ppm/K	± 1 %	10 Ω to 3.01 MΩ	E24; E96
		± 0.5 %	10 Ω to 3.01 MΩ	E24; E192
		± 0.1 %	47 Ω to 2.13 MΩ	
	± 25 ppm/K	± 1 %	10 Ω to 3.01 MΩ	E24; E96
		± 0.5 %	10 Ω to 3.01 MΩ	E24; E192
		± 0.1 %	47 Ω to 2.13 MΩ	
	± 15 ppm/K	± 0.1 %		
	± 10 ppm/K	± 0.1 %		

PACKAGING

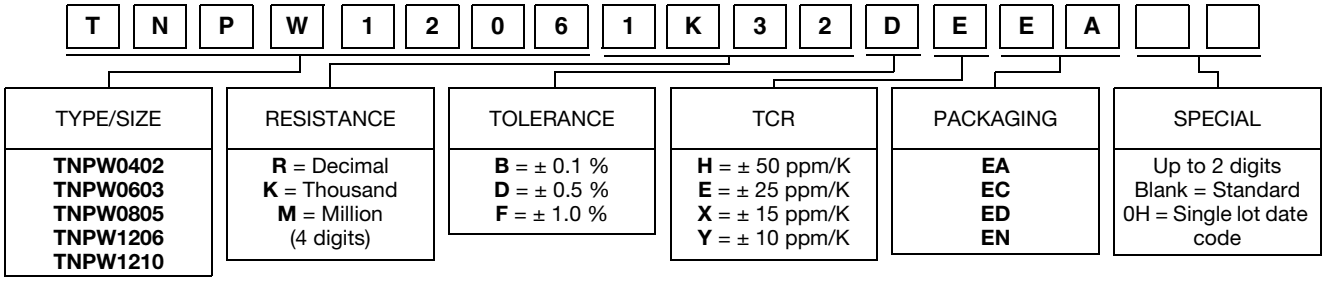
TYPE	CODE	QUANTITY	CARRIER TAPE	WIDTH	PITCH	REEL DIAMETER
TNPW0402 e3	ET7 = ED	10 000	Paper tape acc. IEC 60286-3 Type I	8 mm	2 mm	180 mm/7"
TNPW0603 e3 TNPW0805 e3 TNPW1206 e3 TNPW1210 e3	E52 = EN	1000 (1)			4 mm	180 mm/7"
	ET1 = EA	5000				
	ET6 = EC	20 000			4 mm	330 mm/13"

Note

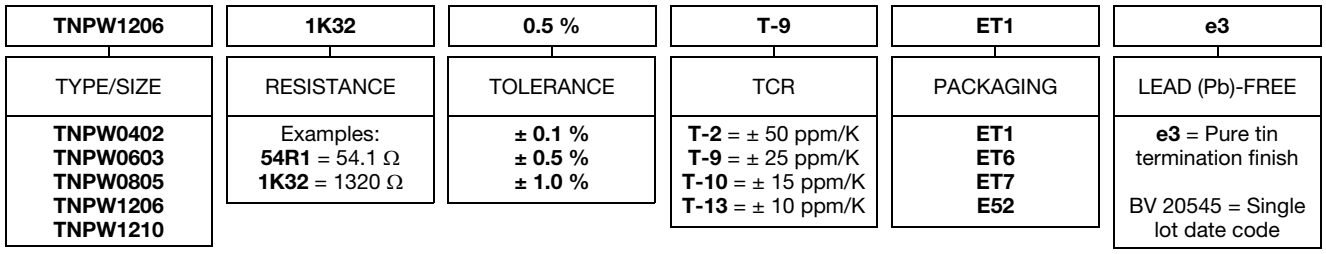
(1) 1000 pieces packaging is available only for precision resistors with tolerance ± 0.1 % and temperature coefficient ≤ ± 25 ppm/K.

PART NUMBER AND PRODUCT DESCRIPTION

Part Number: TNPW12061K32DEEA



Product Description: TNPW1206 1K32 0.5 % T-9 ET1 e3



Note

- The product can be ordered using either the PART NUMBER or the PRODUCT DESCRIPTION.

DESCRIPTION

Production is strictly controlled and follows an extensive set of instructions established for reproducibility. A homogeneous film of special metal alloy is deposited on a high grade (Al_2O_3) ceramic substrate and conditioned to achieve the desired temperature coefficient. Specially designed inner contacts are deposited on both sides. A special laser is used to achieve the target value by smoothly fine trimming the resistive layer without damaging the ceramics. A further conditioning is applied in order to stabilize the trimming result. The resistor elements are covered by a protective coating designed for electrical, mechanical and climatic protection. The terminations receive a final pure tin on nickel plating.
The result of the determined production is verified by an extensive testing procedure on 100 % of the individual chip resistors. This includes full screening for the elimination of products with a potential risk of early life failures according to EN 140401-801, 2.1.2.2. Only accepted products are laid directly into the tape in accordance with **EN 60286-3**.

ASSEMBLY

The resistors are suitable for processing on automatic SMD assembly systems. They are suitable for automatic soldering using wave, reflow or vapour phase as shown in **IEC 61760-1**. The encapsulation is resistant to all cleaning solvents commonly used in the electronics industry, including alcohols, esters and aqueous solutions. The suitability of conformal coatings, if applied, shall be qualified by appropriate means to ensure the long-term stability of the whole system.
The resistors are RoHS-compliant, the pure tin plating provides compatibility with lead (Pb)-free and lead-containing soldering processes. The immunity of the plating against tin whisker growth has been proven under extensive testing.

All products comply with the **JIG 101** list of legal restrictions on hazardous substances.

This includes full compliance with the following directives:

- 2000/53/EC End of Life Vehicle Directive (ELV) and Annex II (ELV II)
- 2011/65/EU Restriction of the use of Hazardous Substances Directive (RoHS)
- 2002/96/EC Waste Electrical and Electronic Equipment Directive (WEEE)

The resistors are Halogen-free according to JEDEC JS709A definition.

Solderability is specified for 2 years after production or re-qualification. The permitted storage time is 20 years.

RELATED PRODUCTS

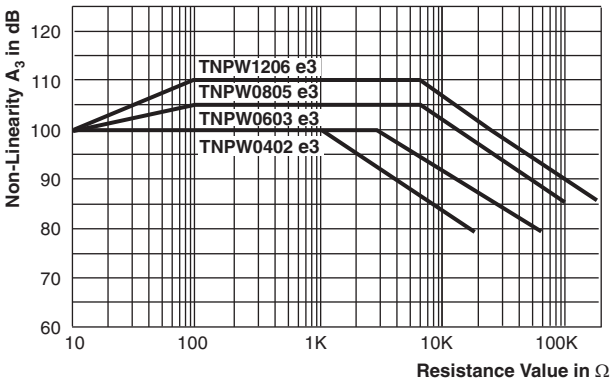
The TNPW with SnPb termination plating is designed for those applications, where lead bearing terminations are mandatory. For ordering TNPW with SnPb terminations please refer to latest edition of datasheet TNPW, document number 31006.

TNPU e3 ultra precision thin film flat chip resistors combine the proven reliability of TNPW e3 products with a most advanced level of precision and stability, document number 28779.

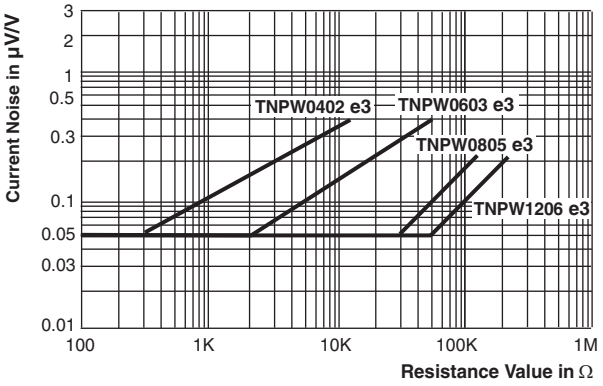
TNPS .... ESCC high-reliability thin film chip resistors are the premium choice for design and manufacture of equipment, where matured technology and proven reliability are of utmost importance. They are regularly used in communication and research satellites and fit equally well into aircraft and military electronic systems.

Approval of the TNPS .... ESCC products is granted by the European Space Components Coordination and registered in the ESCC Qualified Parts List, REP005, document number 28789.

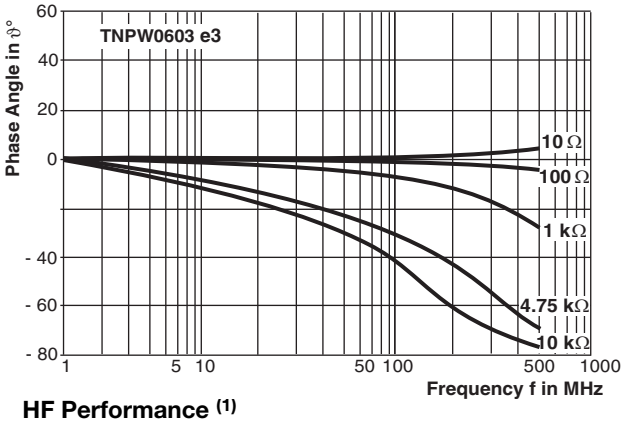
FUNCTIONAL PERFORMANCE



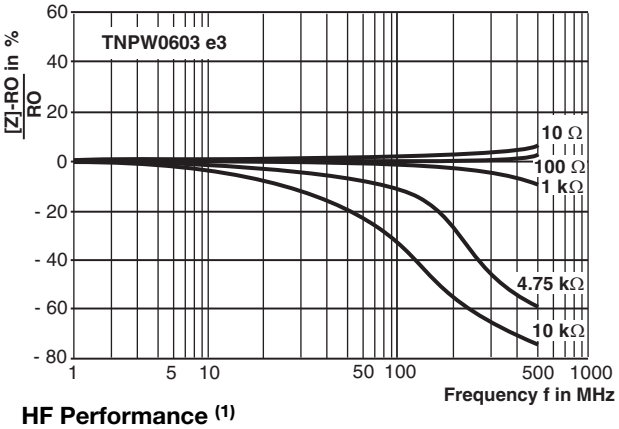
Non-Linearity



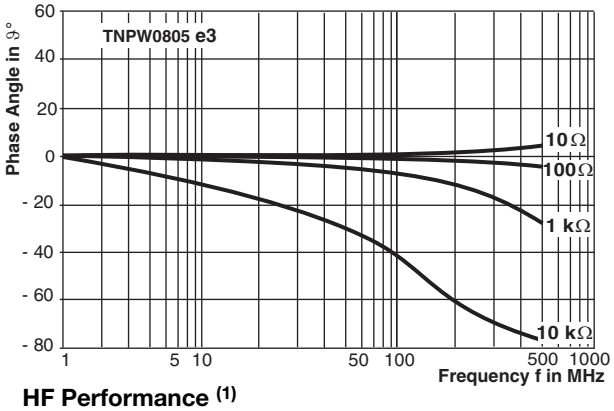
Current Noise



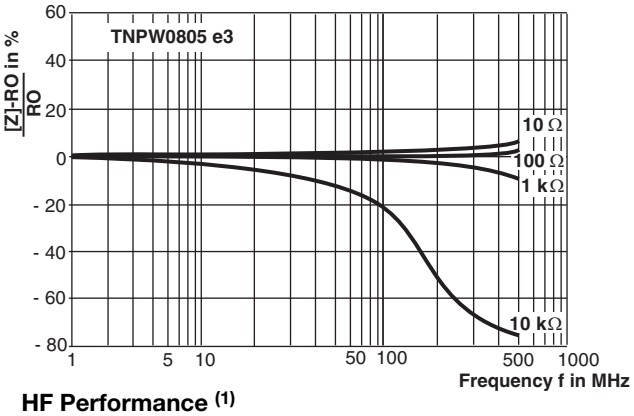
HF Performance (1)



HF Performance (1)



HF Performance (1)

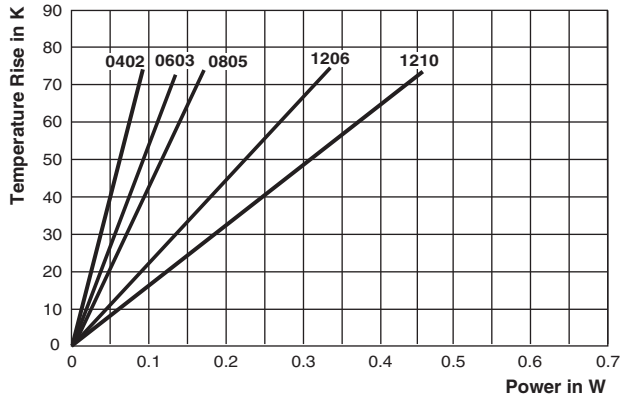


HF Performance (1)

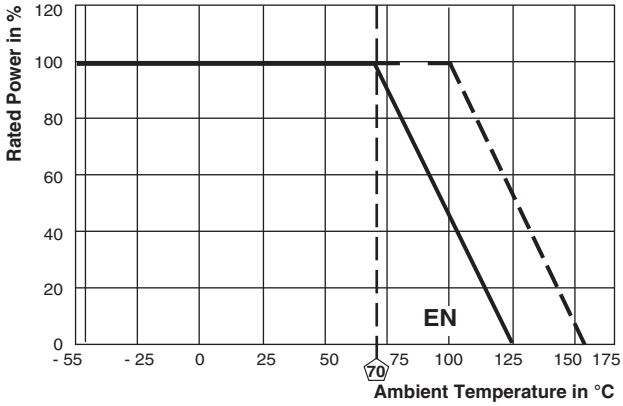
Note

(1) Typical figures. HF-characteristic also depends on termination and circuit design.

FUNCTIONAL PERFORMANCE



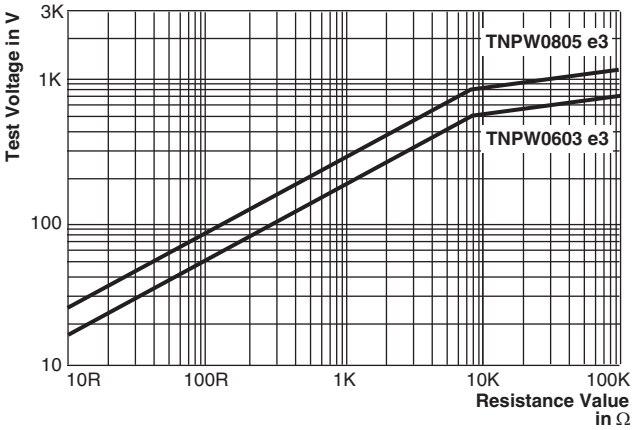
Temperature Rise



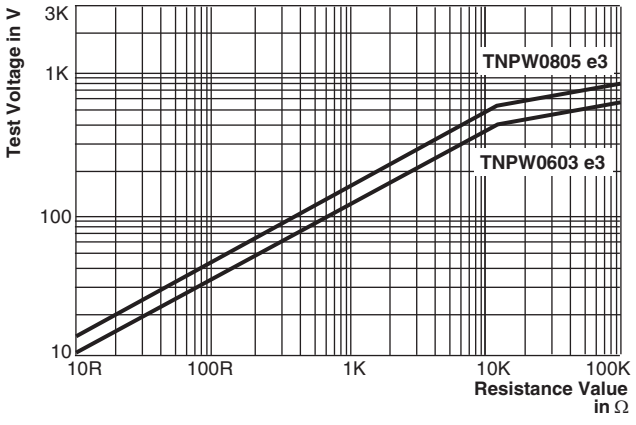
Derating

Note

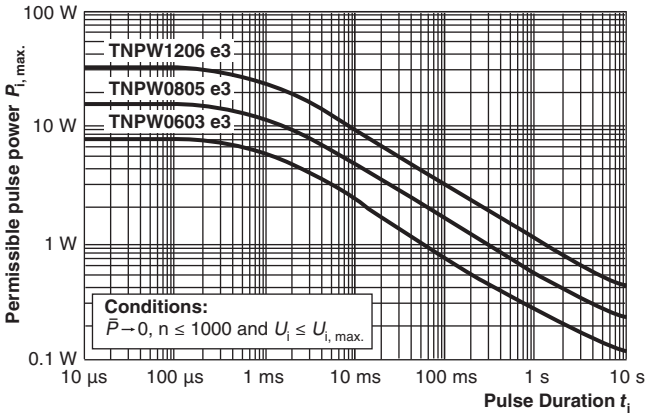
• The solid line is based on IEC/EN reference test conditions which is considered as standard mode. However, above that the maximum permissible film temperature is 155 °C (dashed line).



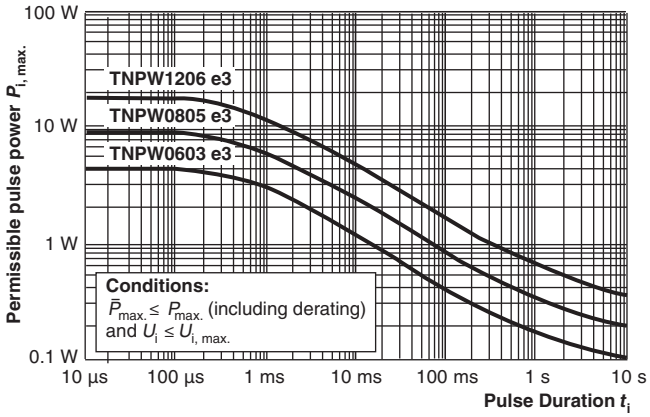
Single-Pulse High Voltage Overload Test 1.2/50 µs EN140000 4.27



Single-Pulse High Voltage Overload Test 10/700 µs EN140000 4.27

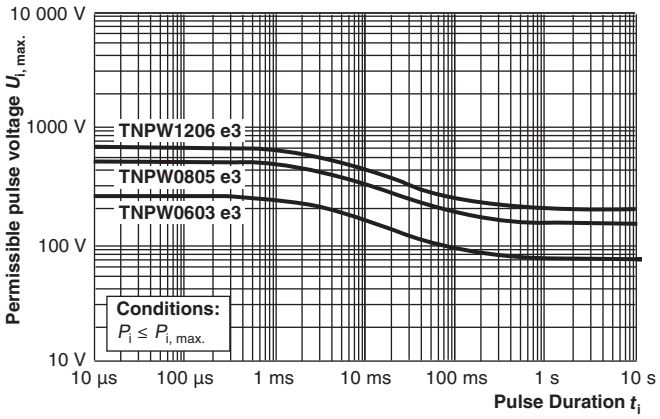


Maximum Pulse Load $P_{i, max.}$ for Single Pulses



Maximum Pulse Load $P_{i, max.}$ for Continuous Pulses

FUNCTIONAL PERFORMANCE



Maximum Pulse Voltage $U_{i, max.}$

TEST AND REQUIREMENTS

All tests are carried out in accordance with the following specifications:

EN 60115-1, generic specification (incluces tests)

EN 140400, sectional specification (includes schedule for qualification approval)

EN 140401-801, detail specification (includes schedule for conformance inspection)

The testing also covers most of the requirements specified by EIA/ECA-703 and JIS-C-5201-1. The tests are carried out under standard atmospheric conditions in accordance with IEC 60068-1, 5.3. A climate category is applied, defined by the lower category temperature (LCT), the upper category temperature (UCT), and the number of days of the damp heat, steady-state test (56).

Unless otherwise specified the following values apply:

Temperature: 15 °C to 35 °C

Relative humidity: 45 % to 75 %

Air pressure: 86 kPa to 106 kPa (860 mbar to 1060 mbar).

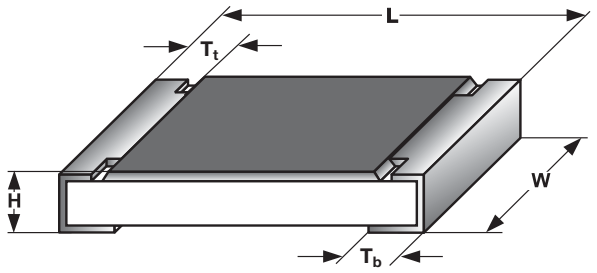
The components are mounted for testing on boards in accordance with EN 60115-1, 4.31 unless otherwise specified. The parameters stated in the Test Procedures and Requirements table are based on the required tests and permitted limits of EN 140401-801.

TEST PROCEDURES AND REQUIREMENTS

EN 60115-1 CLAUSE	IEC 60068-2 TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (ΔR)
			Stability for product types:	
			TNPW0402 e3	
			TNPW0603 e3	
			TNPW0805 e3	
			TNPW1206 e3	
			TNPW1210 e3	
4.5	-	Resistance	-	± 1 %; ± 0.5 %; ± 0.1 %
4.8.4.2	-	Temperature coefficient	At (20/- 55/20) °C and (20/125/20) °C	± 50 ppm/K; ± 25 ppm/K; ± 15 ppm/K; ± 10 ppm/K
4.25.1	-	Endurance at 70 °C	$U = \sqrt{P_{70} \times R}$ or $U = U_{max.}$; whichever is the less severe; 1.5 h on; 0.5 h off;	
			70 °C; 1000 h	± (0.05 % R + 0.01 Ω)
			70 °C; 8000 h	± (0.1 % R + 0.02 Ω)
4.25.3	-	Endurance at upper category temperature	125 °C; 1000 h	± (0.05 % R + 0.01 Ω)
			155 °C; 1000 h	± (0.1 % R + 0.02 Ω)
4.24	78 (Cab)	Damp heat, steady state	(40 ± 2) °C; 56 days; (93 ± 3) % RH	± (0.1 % R + 0.01 Ω)

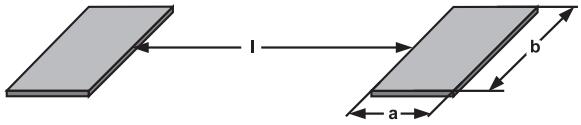
TEST PROCEDURES AND REQUIREMENTS				
EN 60115-1 CLAUSE	**IEC 60068-2 TEST METHOD**	**TEST**	**PROCEDURE**	**REQUIREMENTS PERMISSIBLE CHANGE (ΔR)**
			Stability for product types:	
			TNPW0402 e3	
			TNPW0603 e3	
			TNPW0805 e3	
			TNPW1206 e3	
			TNPW1210 e3	
4.23		Climatic sequence:		± (0.1 % R + 0.02 Ω)
4.23.2	2 (Bb)	Dry heat	UCT; 16 h	
4.23.3	30 (Db)	Damp	55 °C; 24 h; ≥ 90 % RH; 1 cycle	
4.23.4	1 (Ab)	Cold	LCT; 2 h	
4.23.5	13 (M)	Low air pressure	8.5 kPa; 2 h; 25 ± 10 °C	
4.23.6	30 (Db)	Damp heat, cyclic	55 °C; 5 days; ≥ 90 % RH; 5 cycles	
4.23.7	-	DC load	$U = \sqrt{P_{70} \times R} \leq U_{max.}$; 1 min LCT = - 55 °C UCT = 125 °C	
-	1 (Ab)	Cold	- 55 °C; 2 h	± (0.05 % R + 0.01 Ω)
4.19	14 (Na)	Rapid change of temperature	30 min at LCT and 30 min at UCT; LCT = - 55 °C; UCT = 125 °C; 1000 cycles	± (0.1 % R + 0.01 Ω)
4.13	-	Short time overload	$U = 2.5 \times \sqrt{P_{70} \times R}$ or $U = 2 \times U_{max.}$; whichever is the less severe; 5 s	± (0.05 % R + 0.01 Ω)
4.27	-	Single pulse high voltage overload	Severity no. 4: $U = 10 \times \sqrt{P_{70} \times R}$ or $U = 2 \times U_{max.}$; whichever is the less severe; 10 pulses 10 µs/700 µs	± (0.5 % R + 0.02 Ω) no visible damage
4.37	-	Periodic electric overload	$U = \sqrt{15 \times P_{70} \times R}$ or $U = 2 \times U_{max.}$; whichever is the less severe; 0.1 s on; 2.5 s off; 1000 cycles	± (0.5 % R + 0.05 Ω) no visible damage
4.22	6 (Fc)	Vibration	Endurance by sweeping; 10 Hz to 2000 Hz; no resonance; amplitude ≤ 1.5 mm or ≤ 200 m/s^2; 7.5 h	± (0.05 % R + 0.01 Ω) no visible damage
4.17.2	58 (Td)	Solderability	Solder bath method; SnPb40; non-activated flux (215 ± 3) °C; (3 ± 0.3) s	Good tinning (≥ 95 % covered); no visible damage
			Solder bath method; SnAg3Cu0.5 or SnAg3.5; non-activated flux (235 ± 3) °C; (2 ± 0.2) s	
4.18.2	58 (Td)	Resistance to soldering heat	Solder bath method; (260 ± 5) °C; (10 ± 1) s	± (0.02 % R + 0.01 Ω)
4.29	45 (XA)	Component solvent resistance	Isopropyl alcohol + 50 °C; method 2	No visible damage
4.32	21 (Ue_3)	Shear (adhesion)	RR 1005M and RR 1608M; 9 N	No visible damage
			RR 2012M and RR 3216M: 45 N	
4.33	21 (Ue_1)	Substrate bending	Depth 2 mm, 3 times	± (0.05 % R + 0.01 Ω) no visible damage, no open circuit in bent position
4.7	-	Voltage proof	$U_{RMS} = U_{ins}$; 60 ± 5 s	No flashover or breakdown
4.35	-	Flammability	IEC 60695-11-5, needle flame test; 10 s	No burning after 30 s
-	-	Damp heat, steady state accelerated	(85 ± 5) °C; 56 days (85 ± 5) % RH	± (0.25 R + 0.05 Ω)

DIMENSIONS



DIMENSIONS AND MASS					
TYPE	L (mm)	W (mm)	H (mm)	T_t/T_b (mm)	MASS (mg)
TNPW0402 e3	1.0 ± 0.05	0.5 ± 0.05	0.35 ± 0.05	0.2 ± 0.10	0.65
TNPW0603 e3	1.6 ± 0.10	0.85 ± 0.10	0.45 ± 0.10	0.3 ± 0.20	2
TNPW0805 e3	2.0 ± 0.15	1.25 ± 0.15	0.45 ± 0.10	0.4 ± 0.20	5.5
TNPW1206 e3	3.2 ± 0.15	1.6 ± 0.15	0.55 ± 0.10	0.5 ± 0.25	10
TNPW1210 e3	3.2 ± 0.15	2.45 ± 0.15	0.60 ± 0.15	0.5 ± 0.25	16

SOLDER PAD DIMENSIONS



SOLDER PAD DIMENSIONS						
TYPE	REFLOW SOLDERING			WAVE SOLDERING		
	a (mm)	b (mm)	l (mm)	a (mm)	b (mm)	l (mm)
TNPW0402 e3	0.4	0.6	0.5	-	-	-
TNPW0603 e3	0.5	0.9	1.0	0.9	0.9	1.0
TNPW0805 e3	0.7	1.3	1.2	0.9	1.3	1.3
TNPW1206 e3	0.9	1.7	2.0	1.1	1.7	2.3
TNPW1210 e3	0.9	2.5	2.0	1.1	2.5	2.3

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, “Vishay”), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay’s knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer’s responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer’s technical experts. Product specifications do not expand or otherwise modify Vishay’s terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

Material Category Policy

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.

Общество с ограниченной ответственностью «МосЧип» ИНН 7719860671 / КПП 771901001
Адрес: 105318, г.Москва, ул.Щербаковская д.3, офис 1107

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

http://moschip.ru/get-element

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:
moschip.ru
moschip.ru_4
moschip.ru_6
moschip.ru_9